



IEEE EMC Society
Chicago Chapter

[February 15, 2012](#)

Attendees Confirmation for Professional Engineering Credit

Speaker: Colin Tong Laird Technologies

Topic: Advanced Materials and Design for Board Level EMI Shielding

Description of Talk:

The continued miniaturization of surface-mounted devices and the increasing density of the printed circuit board (PCB) have made it necessary to shield different zones of a device from each other, to meet the EMC requirement in electronic system.

Biography:

Colin Tong is Senior Materials Scientist at Laird Technologies. He has involved in developing novel EMI shielding materials, and supporting the manufacturing process, with engineering responsibility for EMI shielding products including spring gaskets, electrically conductive polymer matrix composites, knitted wire mesh shields, metal foam and honeycomb waveguides, and board level shields.

Location

**Illinois Institute of Technology
Rice Campus
201 East Loop Road
Wheaton, Illinois 60189**

Attendee

A handwritten signature in black ink, appearing to read 'Jack Black'. The signature is written in a cursive, flowing style.

Jack Black

Chapter Chairman